

layer, wherein the conductor circuit is comprised of an electroless plated film and an electrolytic plated film, and a roughened layer on at least a part of the surface of the conductor circuit.

D<sup>2</sup> 2. (Twice Amended) A multilayer printed circuit board comprising a plurality of interlaminar insulating layers and conductor circuits, said printed circuit board being formed by laminating a first interlaminar insulating layer on a conductor circuit of a substrate and repeating formation of conductor circuit and an interlaminar insulating layer on the first interlaminar insulating layer, wherein the conductor circuit is comprised of an electroless plated film and an electrolytic plated film, and a roughened layer on at least a part of the surface of the conductor circuit, and the surface of the roughened layer is covered with a layer of a metal having an ionization tendency of more than copper but not higher than titanium, or a noble metal.

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D<sup>3</sup> 7. (Twice Amended) A method of producing a multilayer printed circuit board comprising subjecting a surface of a substrate to an electroless plating, forming a plating resist thereon, subjecting the substrate to an electrolytic plating, removing the plating resist, etching and removing the electroless plated film beneath the plating resist to form a conductor circuit comprised of the electroless plated film and the electrolytic plated film, forming a roughened layer on at least a part of the surface of the conductor circuit, covering the surface of the roughened layer with a layer of a metal having an ionization tendency of more than copper but not higher than titanium, or a noble metal, and forming an interlaminar insulating layer.

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D<sup>4</sup> 13. (Twice Amended) A printed circuit board provided with a conductor layer comprising an alignment mark, said alignment mark being electrically isolated from the conductor layer, and in which a roughened layer is formed on at least a part of the surface of the conductor layer.